N and P-Channel Enhancement Mode Power MOSFET

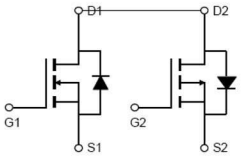
Description

The MJ30NP1812K uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge.
The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications.

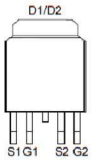
General Features

N channel	p channel
◆ V_{DS}=30V,I_D=18A	V_{DS}=-30V,I_D=-12A
$R_{DS(ON)}$<41mΩ @ V_{GS}=10V	$R_{DS(ON)}$<58mΩ @ V_{GS}=-10V
$R_{DS(ON)}$<54mΩ @ V_{GS}=4.5V	$R_{DS(ON)}$<85mΩ @ V_{GS}=-4.5V

◆ High power and current handing capability
◆ Lead free product is acquired
◆ Surface mount package



Schematic diagram



Marking and pin assignment

100% UIS TESTED! 100% ΔVds TESTED!

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
MJ30NP1812K	MJ30NP1812K	TO-252-4L	-	-	-

Absolute Maximum Ratings (T_A =25 ℃unless otherwise noted)

Parameter		Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage		V_{DS}	30	-30	V
Gate-Source Voltage		V_{GS}	±12	±12	V
Drain Current-Continuou	T_A=25°C	I_D	18	-12	A
	T_A=70°C	I_D	14.4	-8.5	A
Pulsed Drain Current (Note 1)		I_{DM}	72	-48	A
Maximum Power Dissipation	T_A=25°C	P_D	25	25	W
Operating Junction and Storage Temperature Range		T_J,T_{STG}	-55 To 150	-55 To 150	℃

Thermal Characteristic

Thermal Resistance,Junction-to-Case (Note 2)	$R_{\theta JC}$	N-Ch	5	℃/W
Thermal Resistance,Junction-to-Case (Note 2)	$R_{\theta JC}$	P-Ch	5	℃/W

N-Channel Electrical Characteristics (T_A=25℃unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V I_D=250μA	30	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=30V,V_{GS}=0V	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	V_{DS}=±20V,V_{DS}=0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS} ,I_D=250μA	1	1.5	2.0	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	V_{GS}=10V, I_D=10A	-	36	41	mΩ
		V_{GS}=4.5V, I_D=10A	-	45	54	mΩ
Forward Transconductance	g_{FS}	V_{DS}=5V,I_D=10A	-	10	-	S
Dynamic Characteristics (Note 4)						
Input Capacitance	C_{lss}	V_{DS}=15V,V_{GS}=0V, F=1.0MHz	-	519.9	-	PF
Output Capacitance	C_{oss}		-	55.5	-	PF
Reverse Transfer Capacitance	C_{rss}		-	49.3	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	$t_{d(on)}$	V_{DD}=15V, R_L=1.5Ω V_{GS}=10V,R_{GEN}=3Ω	-	5	-	nS
Turn-on Rise Time	t_r		-	3	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	15	-	nS
Turn-Off Fall Time	t_f		-	3	-	nS
Total Gate Charge	Q_g	V_{DS}=15V,I_D=10A V_{GS}=10V	-	14.7	-	nC
Gate-Source Charge	Q_{gs}		-	2.5	-	nC
Gate-Drain Charge	Q_{gd}		-	3.0	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V_{SD}	V_{GS}=0V,I_S=10A	-	0.8	1.2	V

P-CH Electrical Characteristics (T_A=25℃unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V I_D=-250μA	-30	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=-30V,V_{GS}=0V	-	-	-1	μA
Gate-Body Leakage Current	I_{GSS}	V_{DS}=±20V,V_{DS}=0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS} ,I_D=-250μA	-1.0	-1.5	-2.0	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	V_{GS}=-10V, I_D=-12A	-	50	58	mΩ
		V_{GS}=-4.5V, I_D=-10A	-	71	85	mΩ
Forward Transconductance	g_{FS}	V_{DS}=-5V,I_D=-12A	-	10	-	S
Dynamic Characteristics (Note 4)						
Input Capacitance	C_{lss}	V_{DS}=-15V,V_{GS}=0V, F=1.0MHz	-	464.7	-	PF
Output Capacitance	C_{oss}		-	70.4	-	PF
Reverse Transfer Capacitance	C_{rss}		-	53.8	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	$t_{d(on)}$	V_{DD}=-15V, R_L=1.25Ω V_{GS}=-10V,R_{GEN}=6Ω	-	5	-	nS
Turn-on Rise Time	t_r		-	3	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	15	-	nS
Turn-Off Fall Time	t_f		-	4	-	nS
Total Gate Charge	Q_g	V_{DS}=-15V,I_D=-12A V_{GS}=-10V	-	12.6	-	nC
Gate-Source Charge	Q_{gs}		-	2.1	-	nC
Gate-Drain Charge	Q_{gd}		-	3.0	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V_{SD}	V_{GS}=0V,I_S=-12A	-	-	-1.2	V

Notes:

① Repetitive Rating: Pulse width limited by maximum junction temperature.
② Surface Mounted on FR4 Board, t ≤ 10 sec.
③ Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
④ Guaranteed by design, not subject to production.

N- Channel Typical Electrical and Thermal Characteristics (Curves)

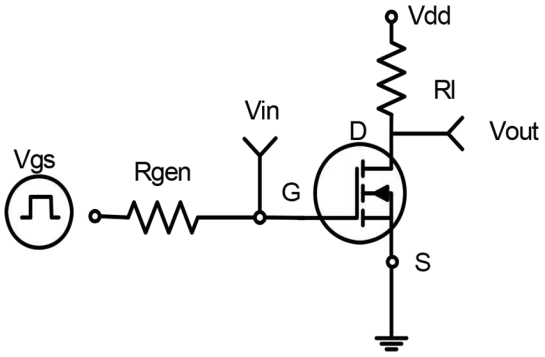


Figure 1 Switching Test Circuit

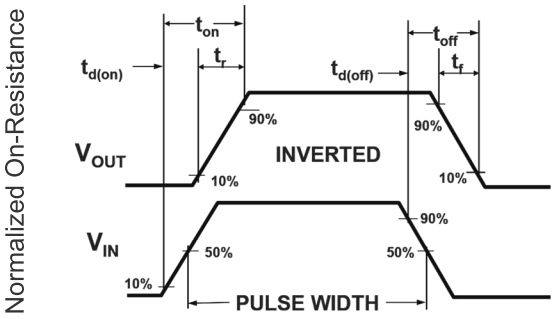


Figure 2 Switching Waveforms

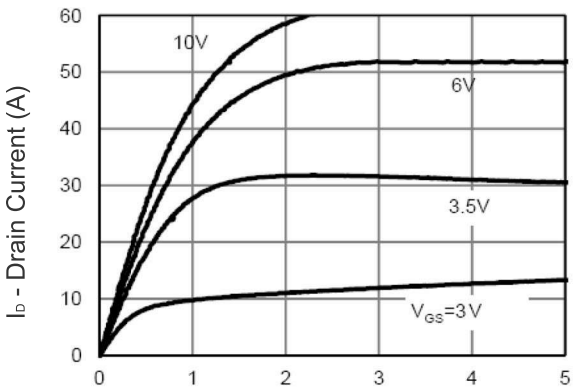


Figure 3 Output Characteristics

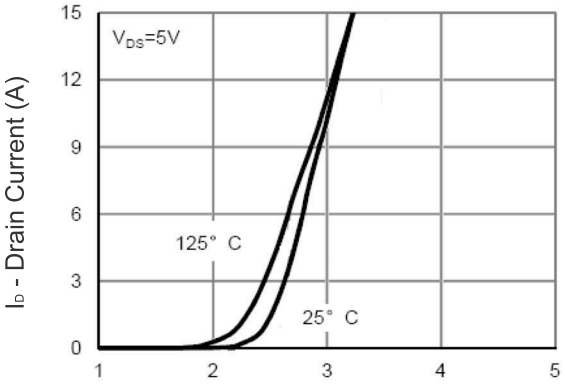


Figure 4 Transfer Characteristics

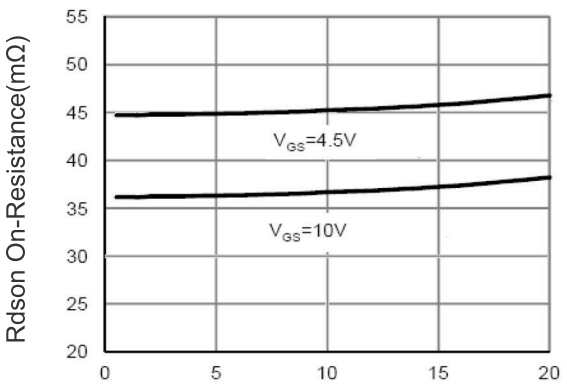


Figure 5 Drain-Source On-Resistance

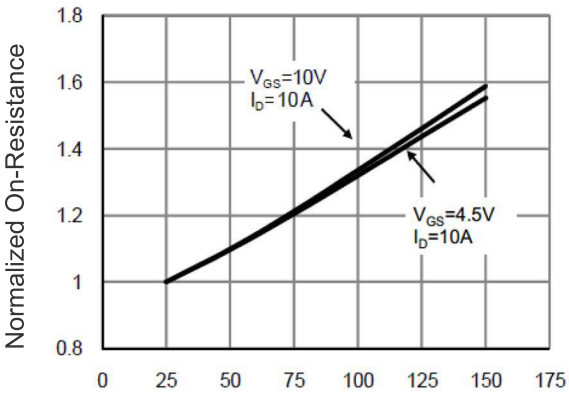


Figure 6 Drain-Source On-Resistance

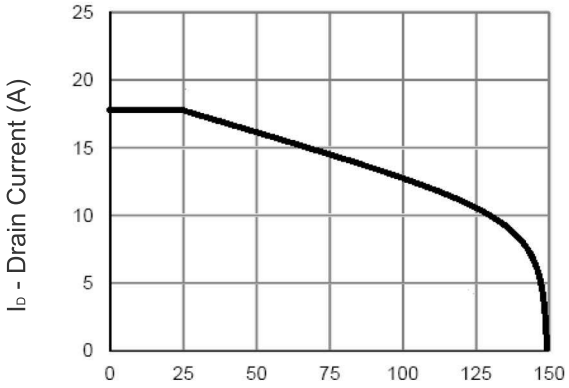


Figure 7 Current De-rating

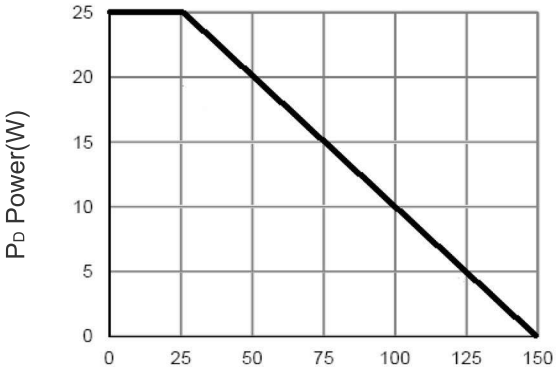


Figure 8 Power Dissipation

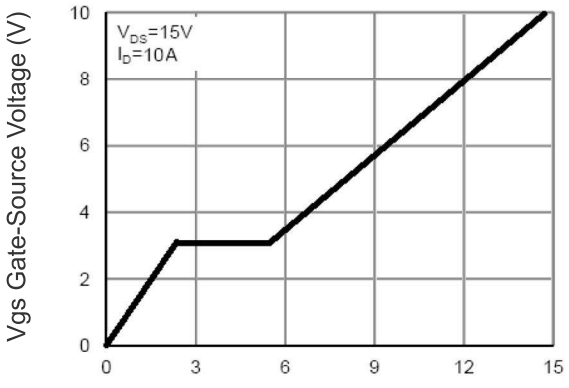


Figure 9 Gate Charge

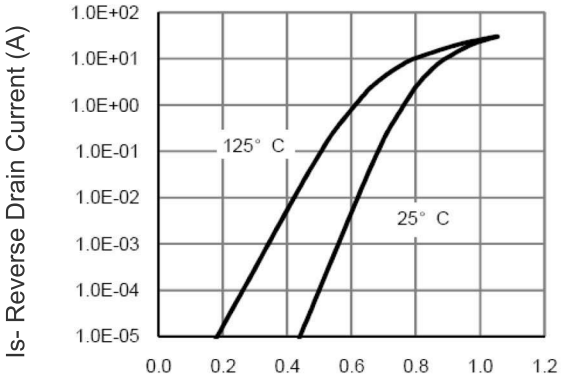


Figure 10 Source- Drain Diode Forward

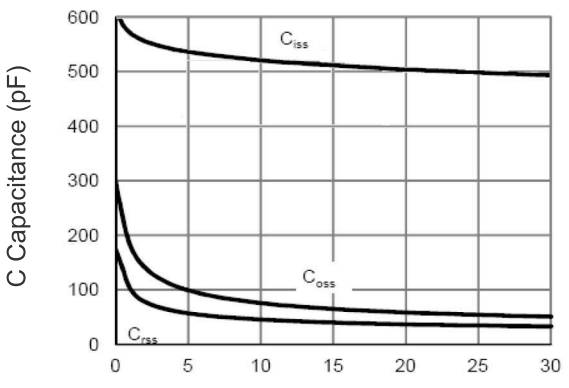


Figure 11 Capacitance vs Vds

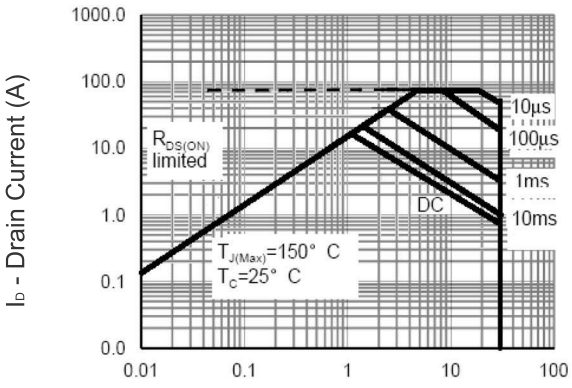


Figure 12 Safe Operation Area

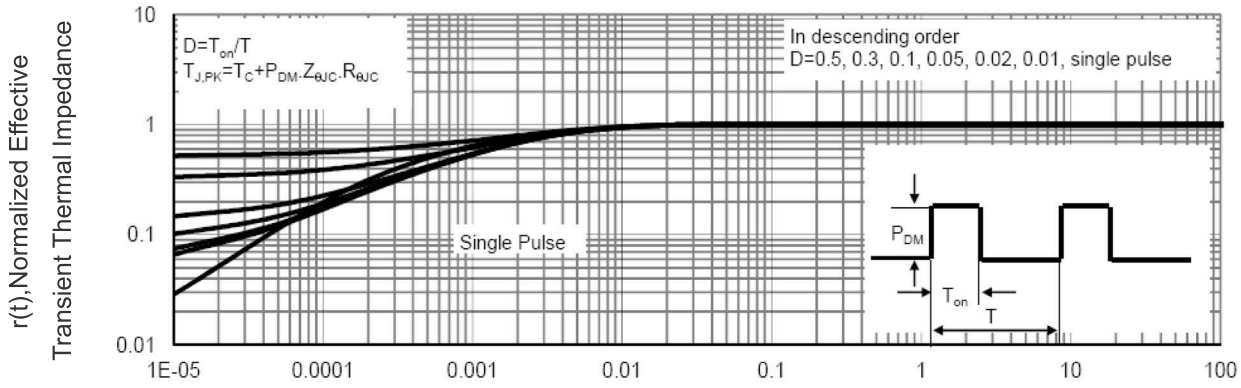


Figure 13 Normalized Maximum Transient Thermal Impedance

P- Channel Typical Electrical and Thermal Characteristics (Curves)

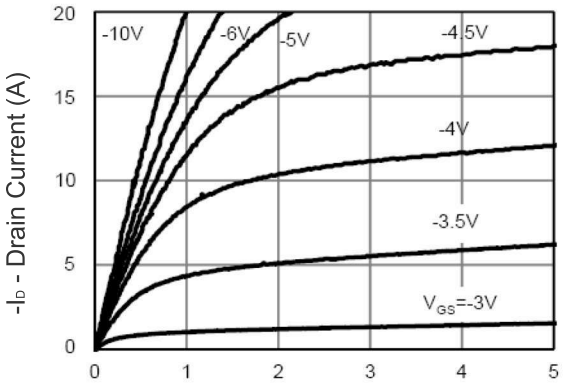


Figure 1 Output Characteristics

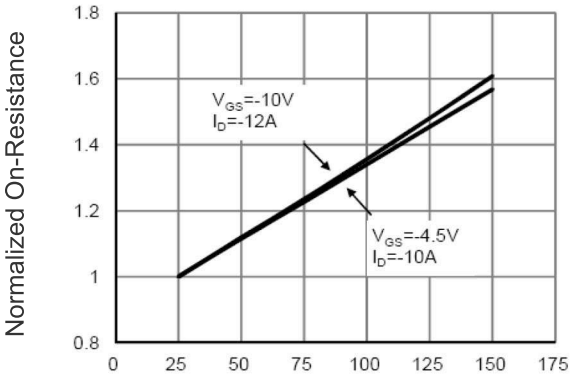


Figure 4 Rdson-Junction Temperature

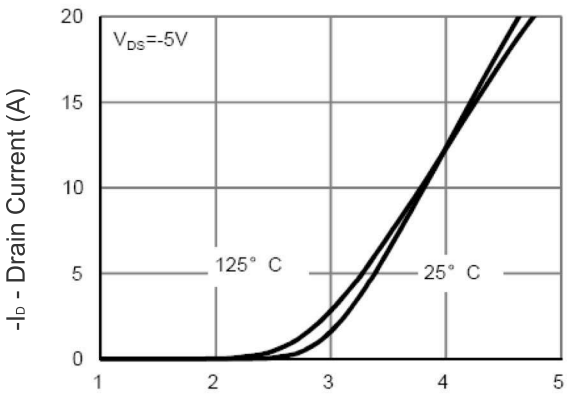


Figure 2 Transfer Characteristics

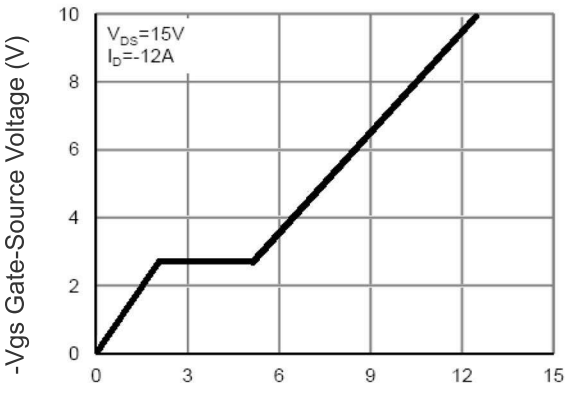


Figure 5 Gate Charge

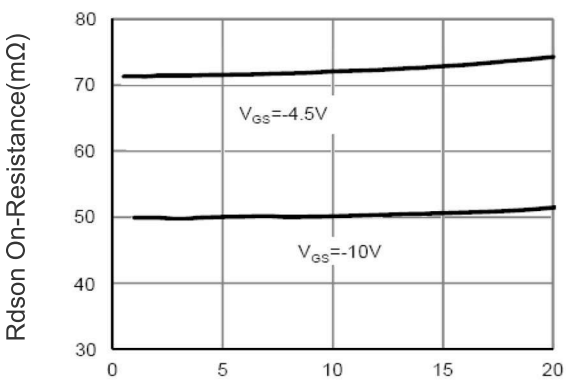


Figure 3 Rdson- Drain Current

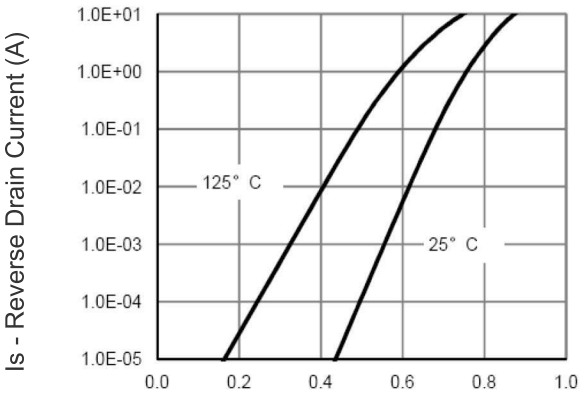


Figure 6 Source- Drain Diode Forward

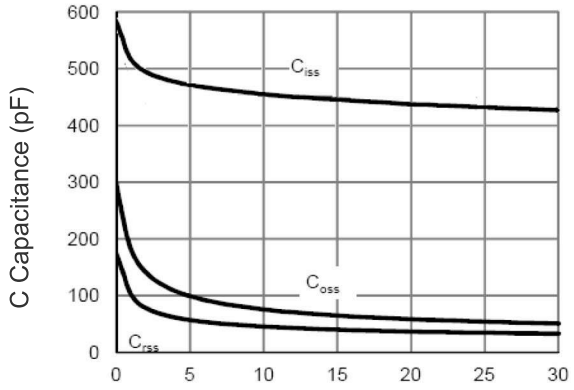


Figure 7 Capacitance vs Vds

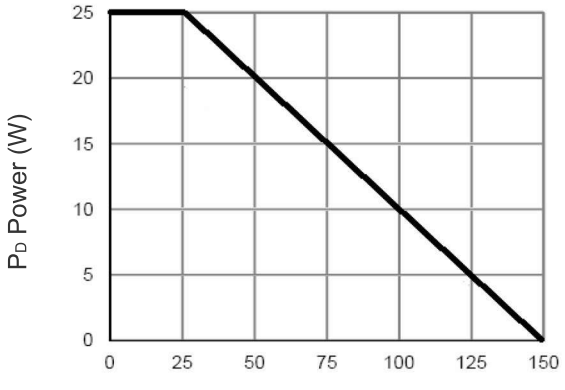


Figure 9 Power Dissipation

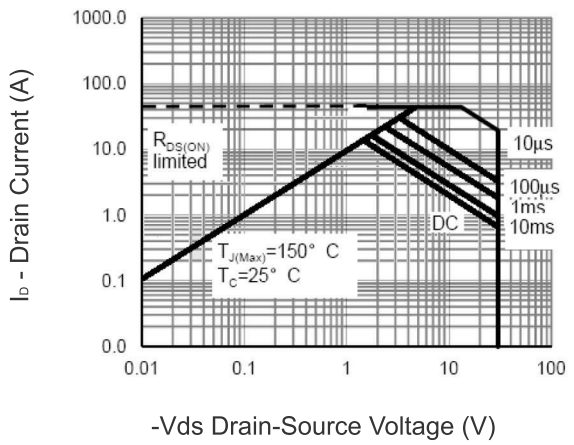


Figure 8 Safe Operation Area

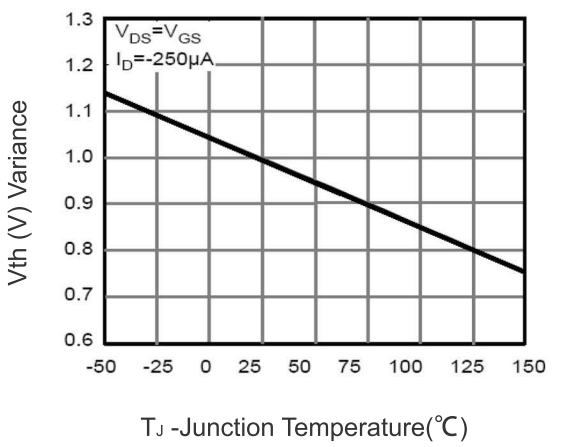


Figure 10 $V_{GS(th)}$ vs Junction Temperature

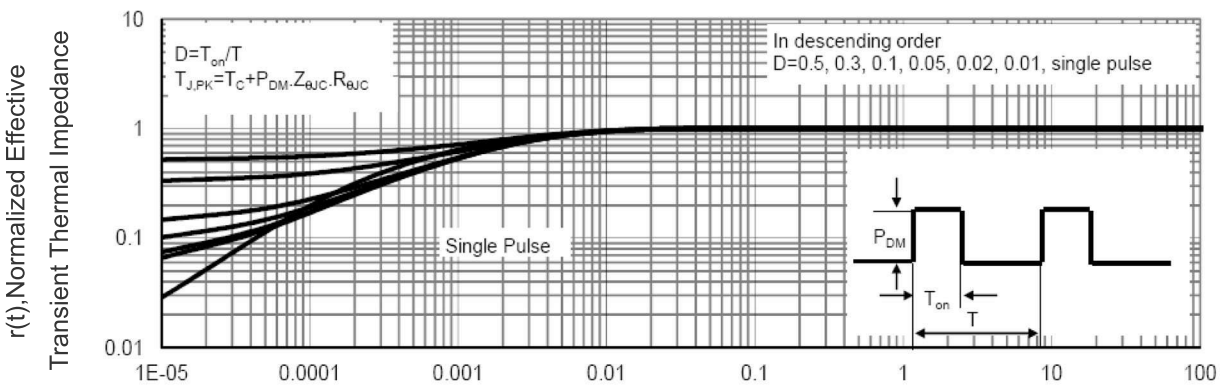
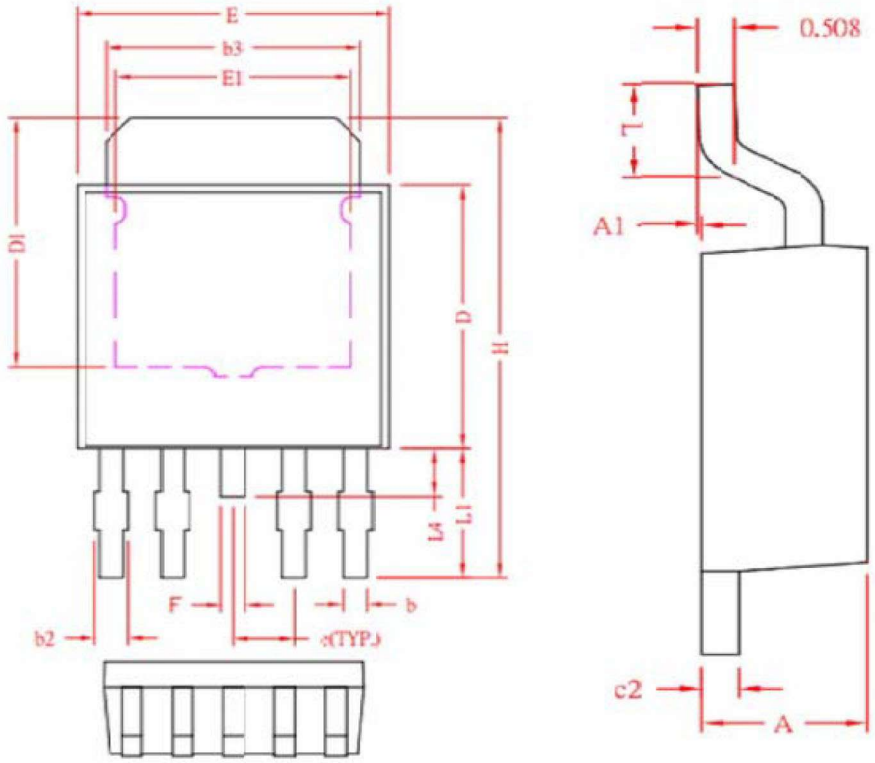


Figure 11 Normalized Maximum Transient Thermal Impedance

TO-252-4L Package Information



COMMON DIMENSIONS
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX
A	2.20	2.30	2.40
A1	0	0.08	0.15
b	0.45	0.53	0.60
b2	0.50	0.65	0.80
b3	5.20	5.35	5.50
c2	0.45	0.50	0.55
D	5.40	5.60	5.80
D1	4.57	-	-
E	6.40	6.60	6.80
E1	3.81	-	-
e	1.27 REF.		
F	0.40	0.50	0.60
H	9.40	9.80	10.20
L	1.40	1.59	1.77
L1	2.40	2.70	3.00
L4	0.80	1.00	1.20

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